

SOT1234

plastic, thermal enhanced super thin outline package; no leads; 6 terminals; 0.4 mm pitch, 1.4 mm x 1.2 mm x 0.32 mm body

5 September 2017

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	HX2SON6
Package type industry code	HX2SON6
Package style descriptive code	HXSON (thermal enhanced extremely thin small outline; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	1-9-2017
Manufacturer package code	SOT1234

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	1.15	-	1.2	1.25	mm
E	package width	1.35	-	1.4	1.45	mm
A	seated height	0.3	-	0.32	0.33	mm
e	nominal pitch	-	-	0.4	-	mm
n ₂	actual quantity of termination	-	-	6	-	



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2. Package outline

HX2SON6: plastic, thermal enhanced super thin small outline package; no leads; 6 terminals; body 1.4 x 1.2 x 0.32 mm

SOT1234

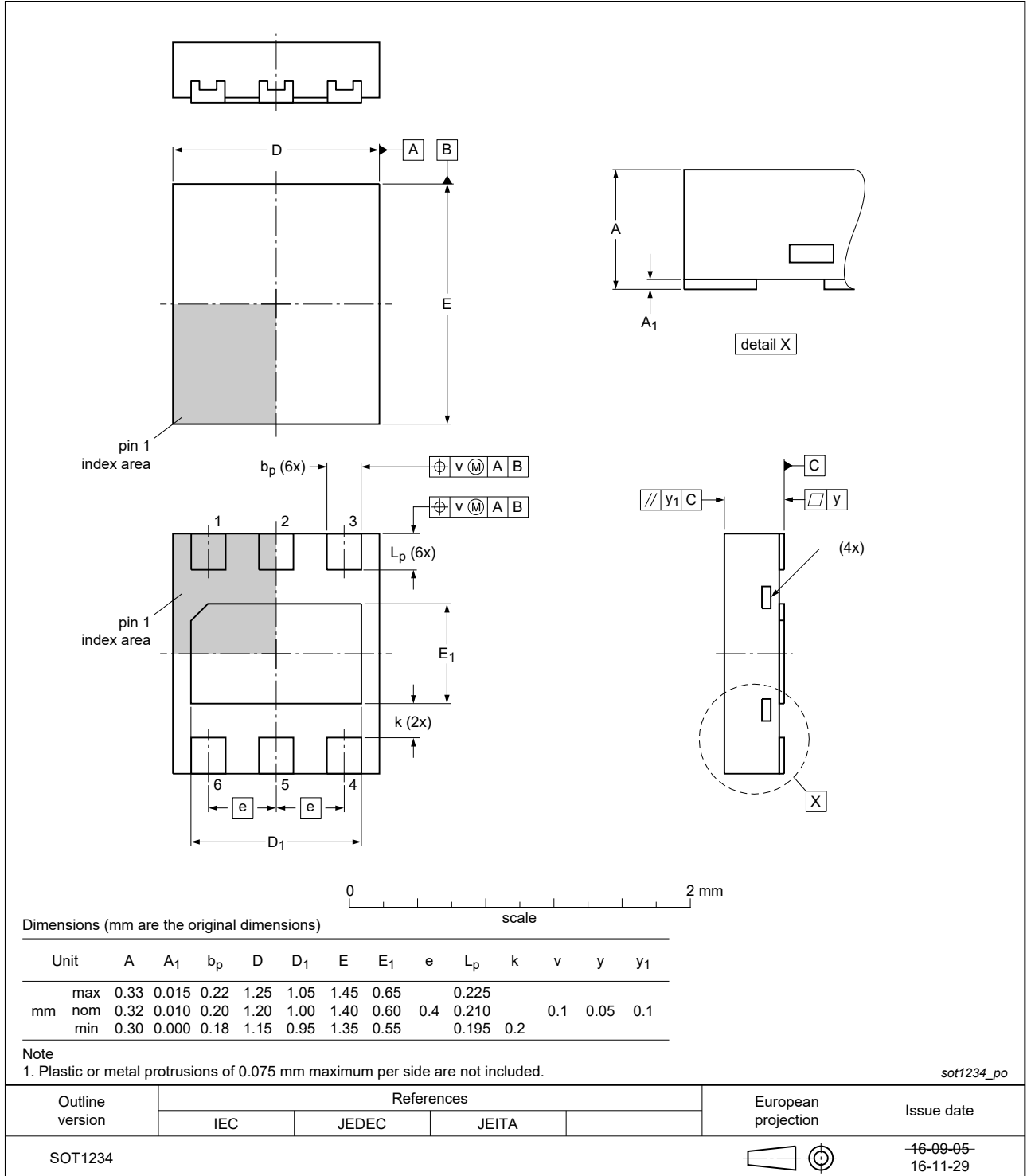


Fig. 1. Package outline HX2SON6 (SOT1234)

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3. Legal information

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4. Contents

1. Package summary.....	1
2. Package outline.....	2
3. Legal information.....	3

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